```
COST IN U.S. DOLLARS
                                                   SINCE FILE
                                                                   TOTAL
                                                                 SESSION
                                                        ENTRY
                                                                    0.21
FULL ESTIMATED COST
                                                         0.21
FILE 'EUROPATFULL' ENTERED AT 13:50:37 ON 15 APR 2003
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FILE 'PATDPAFULL' ENTERED AT 13:50:37 ON 15 APR 2003
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FILE 'USPATFULL' ENTERED AT 13:50:37 ON 15 APR 2003
CA INDEXING COPYRIGHT (C) 2003 AMERICAN CHEMICAL SOCIETY (ACS)
FILE 'USPAT2' ENTERED AT 13:50:37 ON 15 APR 2003
CA INDEXING COPYRIGHT (C) 2003 AMERICAN CHEMICAL SOCIETY (ACS)
=> s Saito, Noriaki/in
L1
            48 SAITO, NORIAKI/IN
=> s novolak resin# and formaldehyde3 and (phenol or ortho-cresol or 0-cresol)
   3 FILES SEARCHED...
             O NOVOLAK RESIN# AND FORMALDEHYDE3 AND (PHENOL OR ORTHO-CRESOL OR
                0-CRESOL)
=> s novolak resin# and formaldehyde and (phenol or ortho-cresol or o-cresol)
          4266 NOVOLAK RESIN# AND FORMALDEHYDE AND (PHENOL OR ORTHO-CRESOL OR
               O-CRESOL)
=> s 13 and oxalic acid catalyst#
            48 L3 AND OXALIC ACID CATALYST#
=> s 14 and temperature# and pressure
            17 L4 AND TEMPERATURE# AND PRESSURE
=> s 15 and ortho ratio
L6
             1 L5 AND ORTHO RATIO
     ANSWER 1 OF 1 USPATFULL
          racinina
References
ΑN
       2002:172464 USPATFULL
TI
       Method of producing novolak resin
       Saito, Noriaki, Toyonaka-shi, JAPAN
IN
       Aizu, Ichishi, Niihama-shi, JAPAN
       Nakajima, Nobuyuki, Niihama-shi, JAPAN
       Fujiwara, Masahiro, Niihama-shi, JAPAN
       Yano, Koji, Niihama-shi, JAPAN
       SUMITOMO CHEMICAL COMPANY, LIMITED (non-U.S. corporation)
PA
PI
       US 2002091224
                          A1 20020711
       US 2001-364
JP 2000-377258
                                20011204 (10)
                          A1
PRAI
                           20001212
       JP 2000-377259
                            20001212
       JP 2001-153632
                           20010523
DT
       Utility
FS
       APPLICATION
LN.CNT 579
INCL
       INCLM: 528/129.000
NCL
       NCLM: 528/129.000
IC
       [7]
```

ICM: C08G008-04 CAS INDEXING IS AVAILABLE FOR THIS PATENT.

=> d 15 1-17

ANSWER 1 OF 17 EUROPATFULL COPYRIGHT 2003 WILA



PATENT APPLICATION - PATENTANMELDUNG - DEMANDE DE BREVET

```
342035 EUROPATFULL ED 20000917 EW 198946 FS OS STA B
TIEN
       Powdered epoxy resin compositions.
       Pulverfoermige Epoxydharzzusammensetzungen.
TIDE
TIFR
       Compositions de resines epoxydes sous forme de poudre.
       Bymark, Richard M. c/o Minnesota Mining and, Manufacturing Company 3M
TN
       Austin Center, P.O. Box 2963 Austin Texas 78769-2963, US;
       Kirk, Alan R. c/o Minnesota Mining and, Manufacturing Company 2501
       Hudson Road P.O.Box, 33427 St. Paul, Minnesota 55133-3427, US;
       Griggs, Allen L. c/o Minnesota Mining and, Manufacturing Company 2501
       Hudson Road P.O.Box, 33427 St. Paul Minnesota 55133-3427, US;
       Martin, Steven J. c/o Minnesota Mining and, Manufacturing Company 2501
       Hudson Road P.O. Box, 33427 St. Paul, Minnesota 55133-3427, US
       MINNESOTA MINING AND MANUFACTURING COMPANY, P.O. Box 33427, St. Paul
PA
       Minnesota 55133-3427, US
SO
       Wila-EPZ-1989-H46-T1
       R DE; R FR; R GB; R IT
PIT
       EPA2 EUROPAEISCHE PATENTANMELDUNG
PΙ
       EP 342035
                            A2 19891115
\overline{\mathsf{DD}}
                                19891115
                                19890511
       EP 1989-304781
ΑI
PRAI
       US 1988-193498
                               19880512
       ICM C08G059-62
IC
                           C09D005-00
       ICS C09D003-58
```

COPYRIGHT 2003 Univentio ANSWER 2 OF 17 PCTFULL



```
2002031011 PCTFULL ED 20020515 EW 200216
AN
        FRACTIONATION OF RESINS USING A STATIC MIXER AND A LIQUID-LIQUID
TIEN
        CENTRIFUGE
TIFR
        FRACTIONNEMENT DE RESINES AU MOYEN D'UN MELANGEUR FIXE ET D'UNE
        CENTRIFUGEUSE LIQUIDE-LIQUIDE
        WANAT, Stanley, F., 3 Frances Lane, Scotch Plains, NJ 07076, US;
IN
        RAHMAN, M., Dalil, 62 Concord Ridge Road, Flemington, NJ 08822, US;
        XIANG, Zhong, 1142 Easton Avenue, Apartment G, Somerset, NJ 08873, US CLARIANT INTERNATIONAL LTD, Rothausstrasse 61, CH-4132 Muttenz, CH [CH,
PA
        CH], for JP only;
        CLARIANT FINANCE (BVI) LIMITED, Wickhams Cay, P.O. Box 662, Road Town,
        Tortola, VG [-, -], for all designates States except JP HUeTTER, Klaus, Clariant Service GmbH, Patente, Marken, Lizenzen, Am
AG
        Unisys-Park 1, 65843 Sulzbach, DE
LAF
        English
ĽА
        English
DΤ
        Patent
                               A2 20020418
PI
        WO 2002031011
                      CN JP KR SG
DS
       RW (EPO):
                     AT BE CH CY DE DK ES FI FR GB GR IE IT LU MC NL PT SE TR
ΑI
       WO 2001-EP11357
                                A 20011002
           2000-09/687,137
PRAI
        US
                                    20001013
       US 2000-09/698,724
                                   20001027
ICM
        C08G008-00
        B01D017-038; G03F007-023
```

ICS

```
ANSWER 3 OF 17 PCTFULL
                                COPYRIGHT 2003 Univentio
       2000033137 PCTFULL ED 20020515
AN
       PREPARATION OF FRACTIONATED NOVOLAK RESINS BY A NOVEL EXTRACTION
TIEN
       TECHNIQUE
       NOUVELLE TECHNIQUE D'EXTRACTION POUR LA PREPARATION DE RESINES NOVOLAQUE
TIFR
       FRACTIONNEES
       WANAT, Stanley, F.; RAHMAN, Dalil, M.;
TN
       KOKOSZKA, John, J.;
       NARASIMHAN, Balaji
PΑ
       CLARIANT INTERNATIONAL LTD.
I.A
       English
DT
       Patent
       WO 2000033137
                              A2 20000608
PΙ
DS
                    CN JP KR SG AT BE CH CY DE DK ES FI FR GB GR IE IT LU MC NL
       ₩:
                    PT SE
       WO 1999-EP8391
US 1998-09/190,763
AΙ
                              Α
                                 19991103
PRAI
                                 19981112
ICM
       G03F007-023
TCS
       C08G008-08
                                COPYRIGHT 2003 Univentio
     ANSWER 4 OF 17 PCTFULL
ΑN
       1999031157 PCTFULL ED 20020515
       FRACTIONATED NOVOLAK RESIN AND PHOTORESIST COMPOSITION THEREFROM
TIEN
       RESINE NOVOLAK FRACTIONNEE ET COMPOSITION DE RESINE PHOTOSENSIBLE
TIFR
       QU'ELLE PERMET D'OBTENIR
       RAHMAN, M., Dalil;
IN
       COOK, Michelle, M.;
       LU, Ping-Hung
       CLARIANT INTERNATIONAL, LTD.
PΑ
LA
       English
\mathbf{DT}
       Patent
PI
       WO 9931157
                             A1 19990624
                    CN JP KR SG AT BE CH CY DE DK ES FI FR GB GR IE IT LU MC NL
DS
       W:
                    PT SE
       WO 1998-EP7754
                              A 19981201
AΤ
       US 1997-08/991,034
PRAI
                                 19971215
       C08G008-08
ICM
       G03F007-023
ICS
     ANSWER 5 OF 17 USPATFULL
       2003:92961 USPATFULL
AN
TΙ
       Negative photoresist compositions for the formation of thick films,
       photoresist films and methods of forming bumps using the same
TN
       Saito, Koji, Kanagawa, JAPAN
       Misumi, Kouichi, Kanagawa, JAPAN
       Okui, Toshiki, Kanagawa, JAPAN
       Komano, Hiroshi, Kanagawa, JAPAN
TOKYO OHKA KOGYO CO., LTD. (non-U.S. corporation)
PA
       US 2003064319
                           Al 20030403
PΙ
ĀΙ
       US 2002-147984
                           A1
                                 20020520 (10)
PRAI
       JP 2001-151131
                            20010521
DT
       Utility
FS
       APPLICATION
LN.CNT 903
       INCLM: 430/270.100
INCL
       INCLS: 430/325.000
```

```
NCL
         NCLM:
                430/270.100
         NCLS:
                430/325.000
 IC
         [7]
         ICM: G03F007~038
      ANSWER 6 OF 17
                        USPATFULL
           Citing
References
AΝ
         2003:86101 USPATFULL
 TI
         Positive photoresist composition for the formation of thick films,
         photoresist film and method of forming bumps using the same
 IN
        Misumi, Kouichi, Kanagawa, JAPAN
         Saito, Koji, Kanagawa, JAPAN
        Okui, Toshiki, Kanagawa, JAPAN
        Komano, Hiroshi, Kanagawa, JAPAN
TOKYO OHKA KOGYO CO., LTD. (non-U.S. corporation)
 PA
        <u>US 2003059</u>706
ΡI
                              A1
                                    20030327
 \overline{\mathsf{AI}}
        US 2002-90170
                              Α1
                                    20020305 (10)
        JP 2001-61565
 PRAI
                               20010306
DT
        Utility
FS
        APPLICATION
LN.CNT 867
INCL
        INCLM: 430/190.000
        INCLS: 430/189.000; 430/193.000
NCL
                430/190.000
        NCLM:
                430/189.000; 430/193.000
        NCLS:
IC
        [7]
        ICM: G03C001-52
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
      ANSWER 7 OF 17 USPATFULL
L5
           Citine
References
    Full
Text
AN
        2003:26414 USPATFULL
TI
        Fractionation of resins using a static mixer and a liquid-liquid
        centrifuge
        Wanat, Stanley F., Scotch Plains, NJ, United States Rahman, M. Dalil, Flemington, NJ, United States
IN
        Xiang, Zhong, Somerset, NJ, United States
        Clariant Finance (BVI) Limited, VIRGIN ISLANDS (BRITISH) (non-U.S.
PA
        corporation)
        US 6512087
                                    20030128
                              В1
\overline{\mathtt{AI}}
        US 2000-698724
                                    20001027 (9)
RLI
        Continuation-in-part of Ser. No. <u>US 2000-687137</u>, filed on 13 Oct 2000
DT
        Utility
FS
        GRANTED
LN.CNT 947
INCL
        INCLM: 528/502.000D
        INCLS: 528/129.000; 528/148.000; 430/192.000; 430/193.000; 210/634.000
        NCLM: 528/502.000D
NCLS: 210/634.000; 430/192.000; 430/193.000; 528/129.000; 528/148.000
NCL
IC
        [7]
        ICM: C08F006-04
        ICS: G03F007-023
        430/270-1; 430/192; 430/193; 430/325; 430/326; 430/330; 528/148;
EXF
        528/129; 528/502D; 210/634
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
L5
     ANSWER 8 OF 17
                       USPATFULL
   Full
Text
        2002:172464 USPATFULL
AN
TI
       Method of producing novolak resin
IN
       Saito, Noriaki, Toyonaka-shi, JAPAN
```

```
Aizu, Ichishi, Niihama-shi, JAPAN
        Nakajima, Nobuyuki, Niihama-shi, JAPAN
        Fujiwara, Masahiro, Niihama-shi, JAPAN
        Yano, Koji, Niihama-shi, JAPAN
        SUMITOMO CHEMICAL COMPANY, LIMITED (non-U.S. corporation)
PA
        US 2002091224
                            A1 20020711
PI
ĀΙ
        US 2001-364
                             A1
                                  20011204 (10)
        JP 2000-377258
JP 2000-377259
PRAI
                              20001212
                              20001212
        JP 2001-153632
                              20010523
        Utility
DT
FS
        APPLICATION
LN.CNT 579
        INCLM: 528/129.000
NCLM: 528/129.000
INCL
NCL
IC
        [7]
        ICM: C08G008-04
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
     ANSWER 9 OF 17 USPATFULL
L5
           e (etime)
           References
AN
        2000:125188 USPATFULL
TI
        Preparation of fractionated novolak resins by a novel extraction
        Wanat, Stanley F., Scotch Plains, NJ, United States Rahman, M. Dalil, Somerville, NJ, United States
IN
        Kokoszka, John J., Warwick, RI, United States
        Narasimhan, Balaji, Highland Park, NJ, United States
PA
        Clariant Finance (BVI) Limited, Virgin Islands (British) (non-U.S.
        corporation)
        US 6121412
ΡI
                                  20000919
ĀĪ
        US 1999-418239
                                  19991014 (9)
        Continuation-in-part of Ser. No. US 1998-190763, filed on 12 Nov 1998,
RLI
        now abandoned
DТ
        Utility
FS
        Granted
LN.CNT 1037
INCL
        INCLM: 528/502.000D
        INCLS: 528/129.000; 528/144.000; 528/491.000; 430/270.100; 438/455.000;
                438/689.000; 427/352.000; 427/372.200; 210/634.000
NCL
        NCLM:
               528/502.000D
        NCLS:
               210/634.000; 427/352.000; 427/372.200; 430/270.100; 438/455.000;
                438/689.000; 528/129.000; 528/144.000; 528/491.000
        [7]
        ICM: C08F006-04
        ICS: C08F006-22; C08G014-04
EXF
        528/502D; 528/129; 528/144; 528/491; 430/270.1; 427/352; 427/372.2;
        210/634; 438/455; 438/689
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
     ANSWER 10 OF 17 USPATFULL
             (Pielos)
    Full
   Text
          References
AN
        2000:40811 USPATFULL
TI
        Fractionated novolak resin and photoresist composition therefrom
TN
       Rahman, M. Dalil, Flemington, NJ, United States
       Cook, Michelle, Somerville, NJ, United States
       Lu, Ping-Hung, Bridgewater, NJ, United States
Clariant Finance (BVI) Limited, Virgin Islands (British) (non-U.S.
PΑ
       corporation)
       US 6045966
US 1997-991034
                                  20000404
ΑĪ
                                  19971215 (8)
       Utility
```

```
LN.CNT 964
 INCL
        INCLM: 430/270.100
        INCLS: 430/311.000; 528/155.000; 528/165.000
 NCL
               430/270.100
        NCLM:
               430/311.000; 528/155.000; 528/165.000
        NCLS:
 TC
        [7]
        ICM: G03C005-00
 EXF
        528/155; 528/165; 430/270.1; 430/311
 CAS INDEXING IS AVAILABLE FOR THIS PATENT.
      ANSWER 11 OF 17 USPATFULL
           - Billian
    Full
Text
           References
 AN
        97:123007 USPATFULL
 TI
        Positive photoresist coating solution comprising a mixed solvent of
        propylene glycol monopropyl ether and 2-heptanone
        Ohno, Hayato, Kanagawa, Japan
 TN
        Nakao, Taku, Kanagawa, Japan
        Harada, Hisanobu, Kanagawa, Japan
        Hidesaka, Shinichi, Kanagawa, Japan
        Kohara, Hidekatsu, Kanagawa, Japan
        Nakayama, Toshimasa, Kanagawa, Japan
PA
        Tokyo Ohka Kogyo Co., LTD., Kanagawa, Japan (non-U.S. corporation)
\frac{PI}{AI}
        US 5702862
                                 19971230
        US 1997-797663
                                 19970131 (8)
           1996-40461
 PRAI
                            19960202
        Utility
DT
FS
        Granted
LN.CNT 481
INCL
        INCLM: 430/191.000
        INCLS: 430/192.000; 430/193.000
NCL
        NCLM:
              430/191.000
        NCLS:
               430/192.000; 430/193.000
IC
        161
        ICM: G03F007-023
        430/191; 430/192; 430/193
EXF
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
L_5
     ANSWER 12 OF 17 USPATFULL
           ennag
References
AN
        86:52384
                 USPATFULL
TI
       Aromatic carboxylic acid and metal-modified phenolic resins and methods
       of preparation
ΤN
       Ginter, James W., Cheektowaga, NY, United States
       Thorpe, Donald H., Williamsville, NY, United States
       Cooke, Victor F. G., Youngstown, NY, United States
PΑ
       Occidental Chemical Corporation, Niagara Falls, NY, United States (U.S.
       corporation)
       US 4612254
PI
                                19860916
ΑI
       US 1985-709461
                                19850307 (6)
\overline{DT}
       Utility
FS
       Granted
LN.CNT 1586
INCL
       INCLM: 428/531.000
       INCLS: 346/210.000; 346/211.000; 346/212.000; 346/216.000; 346/217.000;
              346/225.000; 428/327.000; 428/326.000; 524/509.000; 524/510.000;
              524/595.000; 524/596.000; 525/506.000; 525/508.000; 528/139.000;
              528/140.000; 528/144.000; 528/146.000; 528/147.000; 528/148.000
NCL
       NCLM:
              503/210.000
       NCLS:
              428/326.000; 428/327.000; 503/211.000; 503/212.000; 503/216.000;
              503/217.000; 503/225.000; 524/509.000; 524/510.000; 524/595.000;
              524/596.000; 525/506.000; 525/508.000; 528/139.000; 528/140.000;
```

FS

Granted

```
528/144.000; 528/146.000; 528/147.000; 528/148.000
IC
        [4]
        ICM: C08G008-32
        ICS: C08L061-14
        525/506; 525/508; 528/148; 528/139; 528/140; 528/144; 528/146; 528/147;
EXF
        524/596; 524/509; 524/510; 524/595; 346/210; 346/211; 346/212; 346/216;
        346/217; 346/225; 428/327; 428/326; 428/531
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
      ANSWER 13 OF 17 USPATFULL
L5
AN
        82:27450 USPATFULL
        Catechol resins for the shell process
ጥፐ
        Craig, Robert S., Hoffman Estates, IL, United States
IN
PΑ
        Acme Resin Corporation, Englewood Cliffs, NJ, United States (U.S.
        corporation)
ΡI
        US 4333513
                                  19820608
ĀΙ
        US 1981-240641
                                  19810305 (6)
        Division of Ser. No. US 1979-90388, filed on 1 Nov 1979, now patented,
RLI
        Pat. No. US 4281090, issued on 8 Jul 1981 which is a division of Ser. No. US 1978-869407, filed on 16 Jan 1978, now patented, Pat. No. US
        4206262, issued on 3 Jun 1980
DT
        Utility
FS
        Granted
LN.CNT 296
INCL
        INCLM: 164/526.000
        INCLS: 264/220.000; 264/221.000
NCL
        NCLM:
               164/526.000
        NCLS: 264/220.000; 264/221.000
IC
        131
        ICM: B22C001-22
        164/526; 264/220; 264/221; 525/501; 260/38
EXF
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
L5
     ANSWER 14 OF 17 USPATFULL
          Seferences
NA
        81:40957 USPATFULL
        Catechol resins for the shell process
TI
IN
        Craig, Robert S., Hoffman Estates, IL, United States
PA
       Acme Resin Corporation, Forest Park, IL, United States (U.S.
        corporation)
PΙ
        US 4281090
                                  19810728
\overline{\mathsf{I}\mathsf{A}}
        US 1979-90388
                                 19791101 (6)
       Division of Ser. No. US 1978-869407, filed on 16 Jan 1978, now patented,
RLI
       Pat. No. US 4206262
DT
       Utility
FS
       Granted
LN.CNT 277
INCL
       INCLM: 525/501.000
       INCLS: 260/038.000
NCL
       NCLM: 525/501.000
       NCLS: 523/145.000; 524/541.000
IC
       [3]
       ICM: C08L061-12
       525/495; 525/501; 528/155; 260/DIG.40; 260/38
EXF
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
L5
     ANSWER 15 OF 17 USPATFULL
            Pelarences
   Text
       80:27035 USPATFULL
AN
       Catechol resins for the shell process
```

8 of 10

```
IN
       Craig, Robert S., Hoffman Estates, IL, United States
       Acme Resin Corporation, Forest Park, IL, United States (U.S.
PA
       corporation)
      us 4206262
                                 19800603
ΡI
                                 19780116 (5)
       US 1978-869407
ĀΙ
DT
       Utility
\Gamma S
       Granted
LN.CNT 290
       INCLM: 428/404.000
INCL
       INCLS: 260/038.000; 428/407.000; 164/043.000
       NCLM: 428/404.000
NCL
       NCLS: 164/021.000; 164/526.000; 428/407.000; 524/448.000
        [2]
IC
       ICM: B32B019-04
       ICS: B32B027-14; B32B027-47
        428/404; 428/407; 428/403; 428/454; 428/524; 260/38; 260/DIG.40; 427/221
EXF
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
     ANSWER 16 OF 17 USPATFULL
             Cleme
    Füll
   Text
          References
       78:7183 USPATFULL
ΑN
ΤI
       Plugging compositions for blast furnace tap holes
       Funabiki, Kyohei, Fujieda, Japan
Tokunaga, Tetsuya, Fujieda, Japan
ΤN
       Sumitomo Durez Company, Ltd., Tokyo, Japan (non-U.S. corporation)
PA
       US 4072531
                                 19780207
PI
AI
       US 1976-666290
                                 19760312 (5)
       Continuation-in-part of Ser. No. US 1975-639679, filed on 11 Dec 1975,
RLI
       now Defensive Publication No.
PRAI
       JP 1975-30669
                            19750315
       Utility
DT
       Granted
LN.CNT 280
INCL
       INCLM: 106/056.000
       INCLS: 106/055.000; 106/058.000; 106/065.000; 106/067.000; 260/038.000
NCT.
       NCLM:
              523/140.000
       NCLS:
               501/099.000; 501/109.000; 501/127.000; 501/128.000; 501/130.000;
               524/594.000
IC
       [2]
       ICM: C04B035-02
       ICS: C04B035-66; C04B035-04; C04B035-66
EXE
       106/56; 106/67; 106/65; 106/58; 106/55; 260/38
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
L5
     ANSWER 17 OF 17 USPATFULL
          citing
References
ΑN
       76:42905 USPATFULL
TI
       Process for preparing phenolic filaments
       Koyama, Hiroaki, Osaka, Japan
IN
PA
       Nippon Kynol Inc., Osaka, Japan (non-U.S. corporation)
PI
       US 3972959
                                 19760803
       US 1974-517029
ĀΪ
                                19741022 (5)
       JP 1973-119673
PRAI
                            19731024
DT
       Utility
FS
       Granted
LN.CNT 741
INCL
       INCLM: 260/841.000
       INCLS: 008/115.500; 260/054.000; 260/055.000; 260/056.000; 260/059.000R;
              260/843.000; 260/847.000; 260/848.000; 264/176.000F; 264/236.000;
              264/347.000
NCL
       NCLM:
              525/429.000
       NCLS: 008/115.560; 264/211.150; 264/211.160; 264/236.000; 264/347.000;
```

wysiwyg://DisplayFrame.RFrame.18/https:/...gi?SID=104348-0738573492-200&APP=stnwcb&

525/160.000; 525/164.000; 525/442.000; 528/493.000; 528/496.000

IC [2]

ICM: D06M013-12

ICS: D06M013-16; D06M013-20 260/59R; 260/841; 264/177F; 264/176F; 264/236; 264/347; 008/115.5 EXF

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

=>